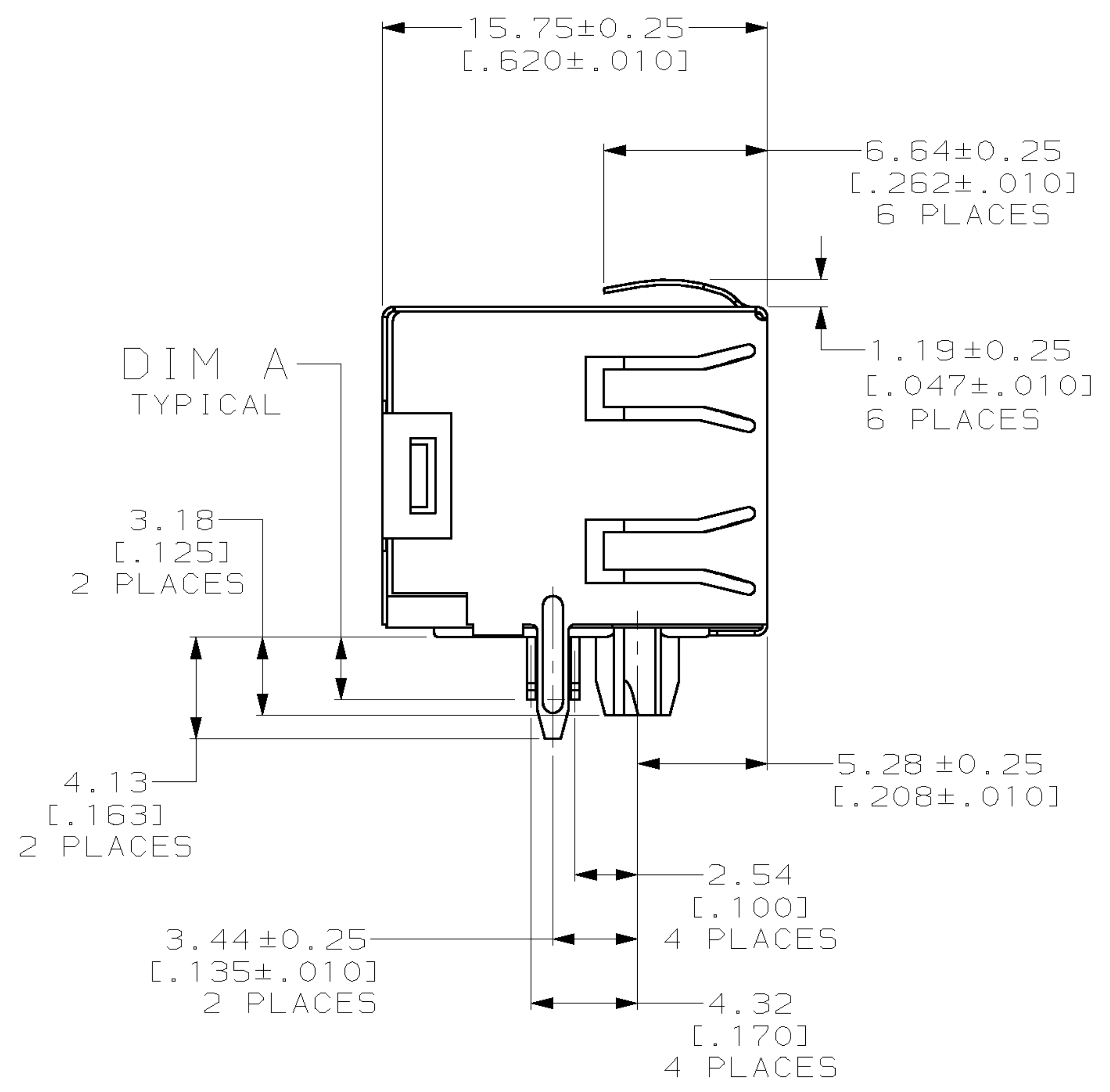
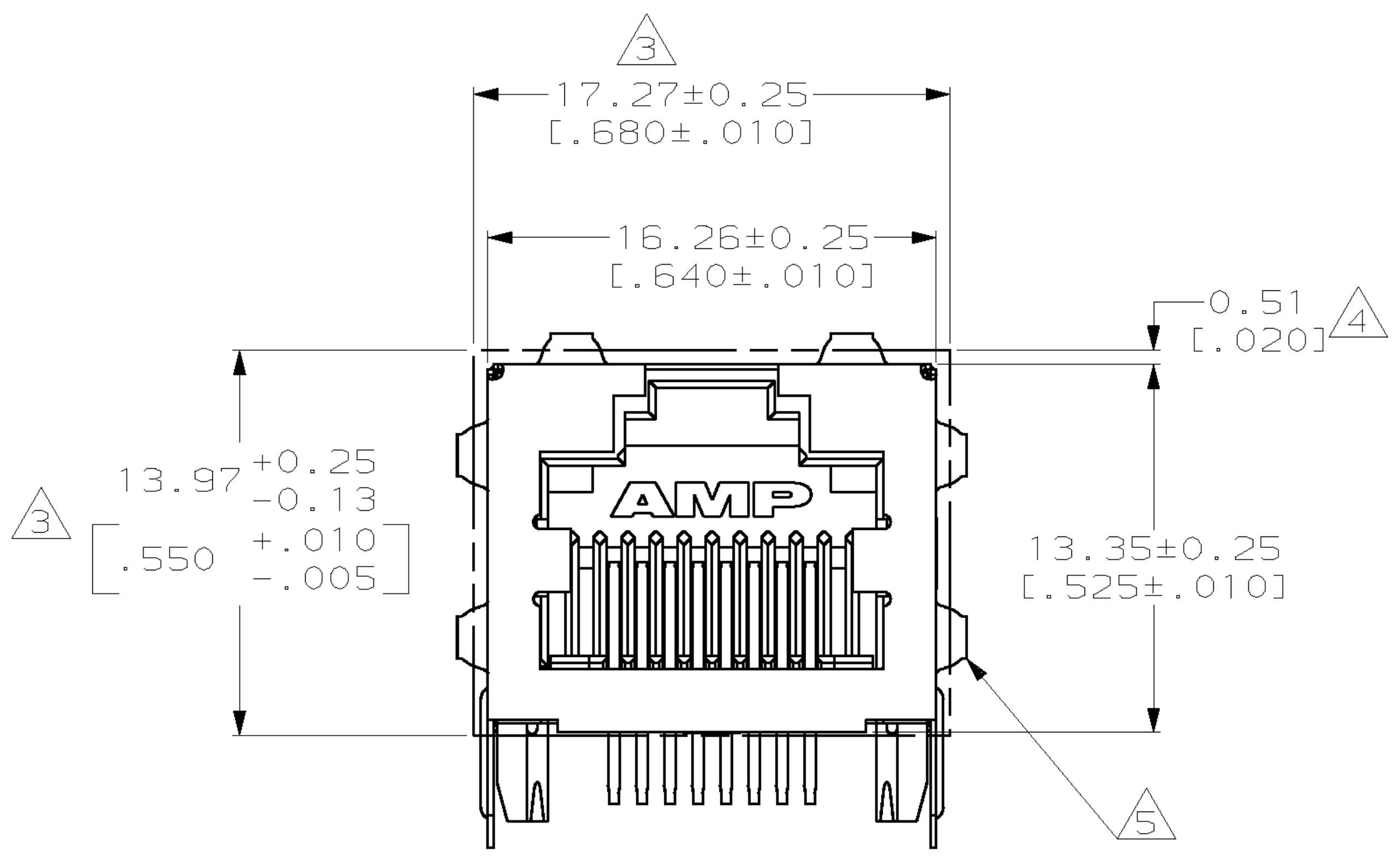
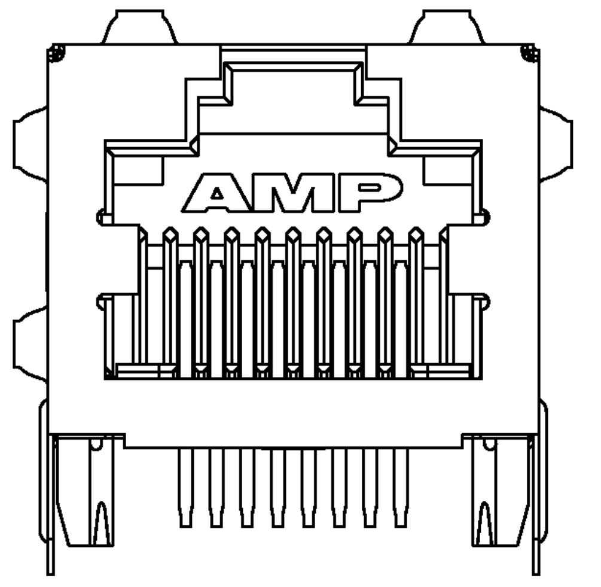
LOC GP DIST 00

REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	G	REVISED PER EC 0S15-0407-02	20DEC02	DD	EL



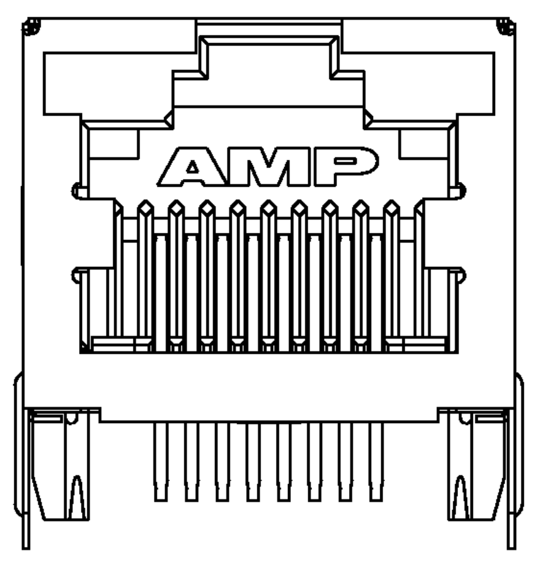


406541-1,-3, & -6

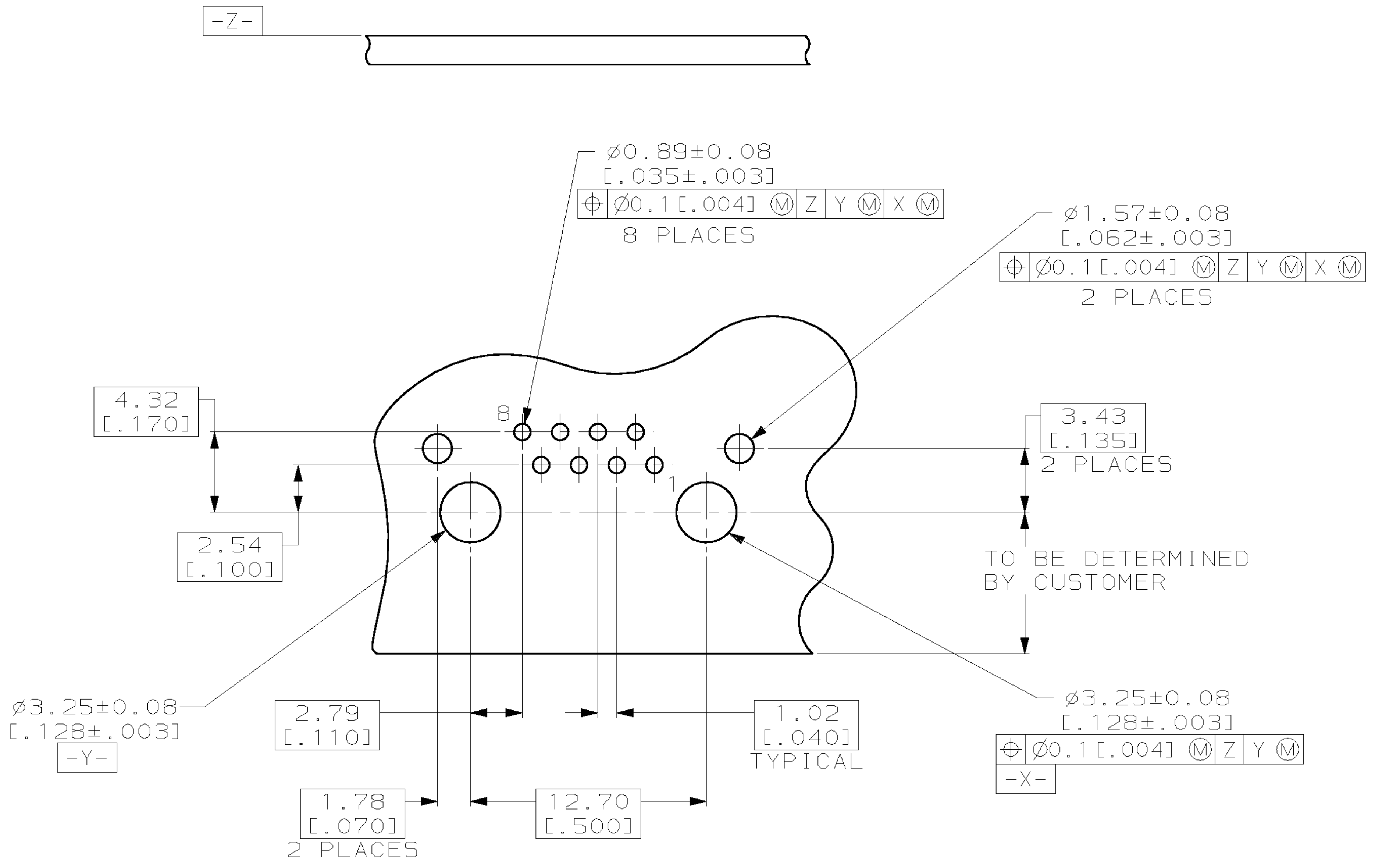


406541-4
VIEW WITHOUT LOWER
RIGHT PANEL GROUND

1. MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; IR REFLOW SOLDERING PROCESS COMPATIBLE.
TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.
SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM TIN-LEAD POST DIPPED ON PCB GROUND TABS.
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIIONS PART 68, SUBPART F.
3. SUGGESTED PANEL OPENING DIMENSIONS.
4. SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
5. ON 406541-4, LOWER RIGHT HAND PANEL GROUND TAB IS NOT PRESENT.



406541-5 6
WITHOUT PANEL GROUNDS



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)

PANEL GROUNDS	DIM A	PART NUMBER
6	3.56[.140]	406541-6
0	2.54[.100]	406541-5
5	2.54[.100]	5 406541-4
6	2.00[.079]	406541-3
6	2.54[.100]	406541-1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:
mm[INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ±-
1 PLC ±-
2 PLC ±0.25[.01]
3 PLC ±0.13[.005]
4 PLC ±-
ANGLES ±-

MATERIAL 1
FINISH 1

DWN 18SEP97 TOM C. SPRINKLE
CHK 18SEP97 TOM C. SPRINKLE
APVD 18SEP97 M. DERSTINE
PRODUCT SPEC 108-1163-4
APPLICATION SPEC 114-2154
WEIGHT -

AMP
AMP Incorporated
Harrisburg, PA 17105-3608

NAME
INVERTED MODULAR JACK ASSEMBLY,
1X1, SHIELDED, PANEL GROUND

SIZE A1
CAGE CODE 00779
DRAWING NO C-406541

CUSTOMER DRAWING
SCALE 4:1
SHEET 1 OF 1
REV G